

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$V_{(\text{BR})\text{DSS}}$	Drain-to-Source Breakdown Voltage	200	—	—	V	$V_{\text{GS}}=0\text{V}$, $I_D = 250\mu\text{A}$
$\Delta V_{(\text{BR})\text{DSS}}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.30	—	V/ $^\circ\text{C}$	Reference to 25°C , $I_D = 1\text{mA}$
$R_{\text{DS}(\text{on})}$	Static Drain-to-Source On-Resistance	—	—	1.5	Ω	$V_{\text{GS}}=10\text{V}$, $I_D = 2.0\text{A}$ ④
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	2.0	—	4.0	V	$V_{\text{DS}}=V_{\text{GS}}$, $I_D = 250\mu\text{A}$
g_{fs}	Forward Transconductance	0.80	—	—	S	$V_{\text{DS}}=50\text{V}$, $I_D = 2.0\text{A}$ ④
I_{DSS}	Drain-to-Source Leakage Current	—	—	25	μA	$V_{\text{DS}}=200\text{V}$, $V_{\text{GS}}=0\text{V}$
		—	—	250		$V_{\text{DS}}=160\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J = 125^\circ\text{C}$
I_{ess}	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{\text{GS}}=20\text{V}$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{\text{GS}}=-20\text{V}$
Q_g	Total Gate Charge	—	—	8.2	nC	$I_D = 3.3\text{A}$
Q_{gs}	Gate-to-Source Charge	—	—	1.8		$V_{\text{DS}}=160\text{V}$
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	—	4.5		$V_{\text{GS}}=10\text{V}$ See Fig. 6 and 13 ④
$t_{\text{d(on)}}$	Turn-On Delay Time	—	8.2	—	ns	$V_{\text{DD}}=100\text{V}$
t_r	Rise Time	—	17	—		$I_D = 3.3\text{A}$
$t_{\text{d(off)}}$	Turn-Off Delay Time	—	14	—		$R_G=24\Omega$
t_f	Fall Time	—	8.9	—		$R_D=30\Omega$ See Figure 10 ④
L_D	Internal Drain Inductance	—	4.5	—	nH	Between lead, 6 mm (0.25in.) from package and center of die contact
L_S	Internal Source Inductance	—	7.5	—		
C_{iss}	Input Capacitance	—	140	—		
C_{oss}	Output Capacitance	—	53	—	pF	$V_{\text{GS}}=0\text{V}$
C_{rss}	Reverse Transfer Capacitance	—	15	—		$V_{\text{DS}}=25\text{V}$ $f=1.0\text{MHz}$ See Figure 5

Source-Drain Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
I_S	Continuous Source Current (Body Diode)	—	—	3.3	A	MOSFET symbol showing the integral reverse p-n junction diode.
I_{SM}	Pulsed Source Current (Body Diode) ①	—	—	10		
V_{SD}	Diode Forward Voltage	—	—	2.0	V	$T_J = 25^\circ\text{C}$, $I_S = 3.3\text{A}$, $V_{\text{GS}} = 0\text{V}$ ④
t_{rr}	Reverse Recovery Time	—	150	310	ns	$T_J = 25^\circ\text{C}$, $I_F = 3.3\text{A}$
Q_{rr}	Reverse Recovery Charge	—	0.60	1.4	μC	$dI/dt = 100\text{A}/\mu\text{s}$ ④
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L_S+L_D)				

Notes:

① Repetitive rating; pulse width limited by max. junction temperature (See Figure 11)

③ $I_{SD} \leq 3.3\text{A}$, $dI/dt \leq 70\text{A}/\mu\text{s}$, $V_{DD} \leq V_{(\text{BR})\text{DSS}}$, $T_J \leq 150^\circ\text{C}$

② $V_{DD}=50\text{V}$, starting $T_J=25^\circ\text{C}$, $L=8.8\text{mH}$
 $R_G=25\Omega$, $I_{AS}=3.3\text{A}$ (See Figure 12)

④ Pulse width $\leq 300\ \mu\text{s}$; duty cycle $\leq 2\%$.